

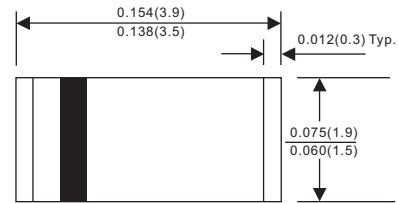


### 1.0A SUFRACE MOUNT SUPER FAST RECTIFIERS - 50-600V SOD-123-L PACKAGE

#### Features

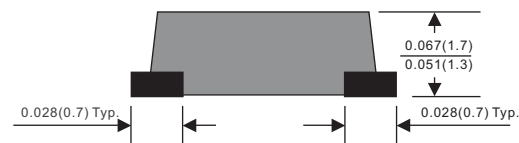
- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- High current capability.
- Superfast recovery time for switching mode application.
- High surge current capability.
- Glass passivated chip junction.
- Moisture Sensitivity Level 1

SOD-123-L



#### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123 / MINI SMA
- Terminals : Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.018 gram



Dimensions in inches and (millimeters)

#### Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = $50^{\circ}\text{C}$	$I_O$			1.0	A
Forward surge current	8.3ms single halfsine-wave superimposed on rate load (JEDEC methode)	$I_{FSM}$			25	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^{\circ}\text{C}$	$I_R$			5.0	uA
	$V_R = V_{RRM}$ $T_A = 100^{\circ}\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		42		$^{\circ}\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		10		pF
Storage temperature		$T_{STG}$	-65		+175	$^{\circ}\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$T_{RR}^{*5}$ (nS)	Operating temperature $T_J$ , ( $^{\circ}\text{C}$ )
SFM11-M	50	35	50	0.95	35	-55 to +150
SFM12-M	100	70	100			
SFM13-M	150	105	150			
SFM14-M	200	140	200	1.25	35	-55 to +150
SFM15-M	300	210	300			
SFM16-M	400	280	400	1.70	35	-55 to +150
SFM17-M	500	350	500			
SFM18-M	600	420	600			

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage
- \*5 Reverse recovery time

#### Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123-L	7"	2,500	4.0	25,000	183*183*123	178	382*262*387	200,000	9.5



### Rating and characteristic curves (SFM11-M THRU SFM18-M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

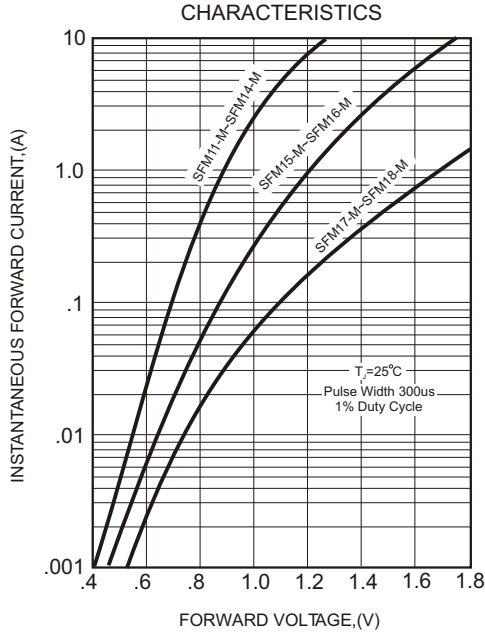


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

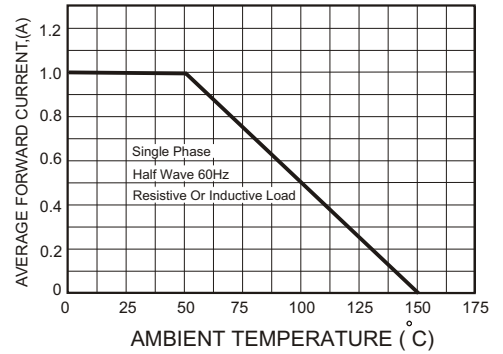


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

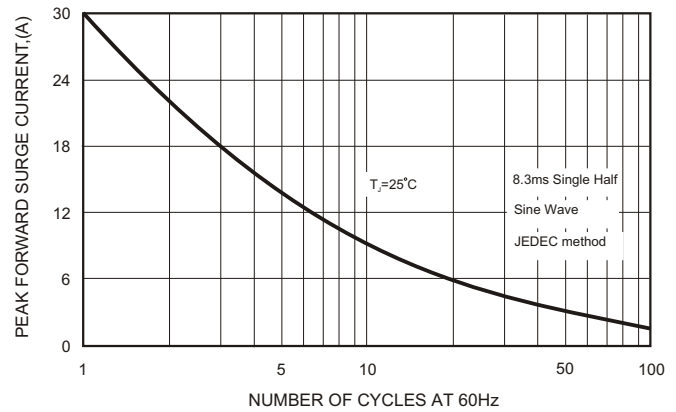
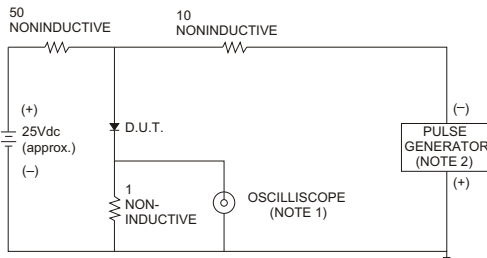


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.  
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

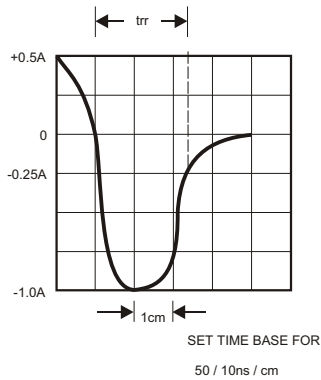
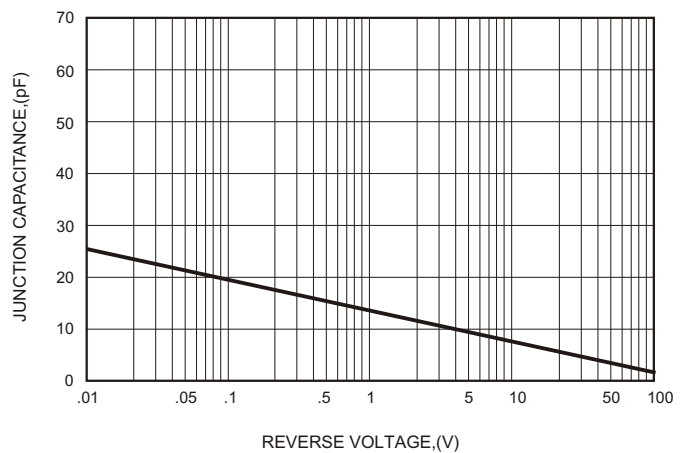


FIG.5-TYPICAL JUNCTION CAPACITANCE





### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code
SFM11-M	S1
SFM12-M	S2
SFM13-M	S3
SFM14-M	S4
SFM15-M	S5
SFM16-M	S6
SFM17-M	S7
SFM18-M	S8

Note: -M: Package code, SOD-123-L

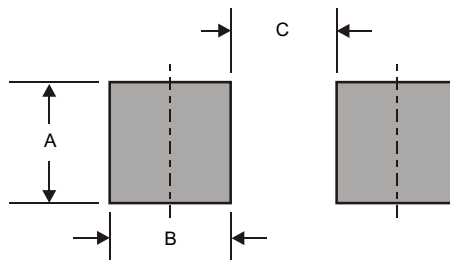
-T: Taping Reel

**Pb-Free package is available**

RoHS product for packing code suffix "G"

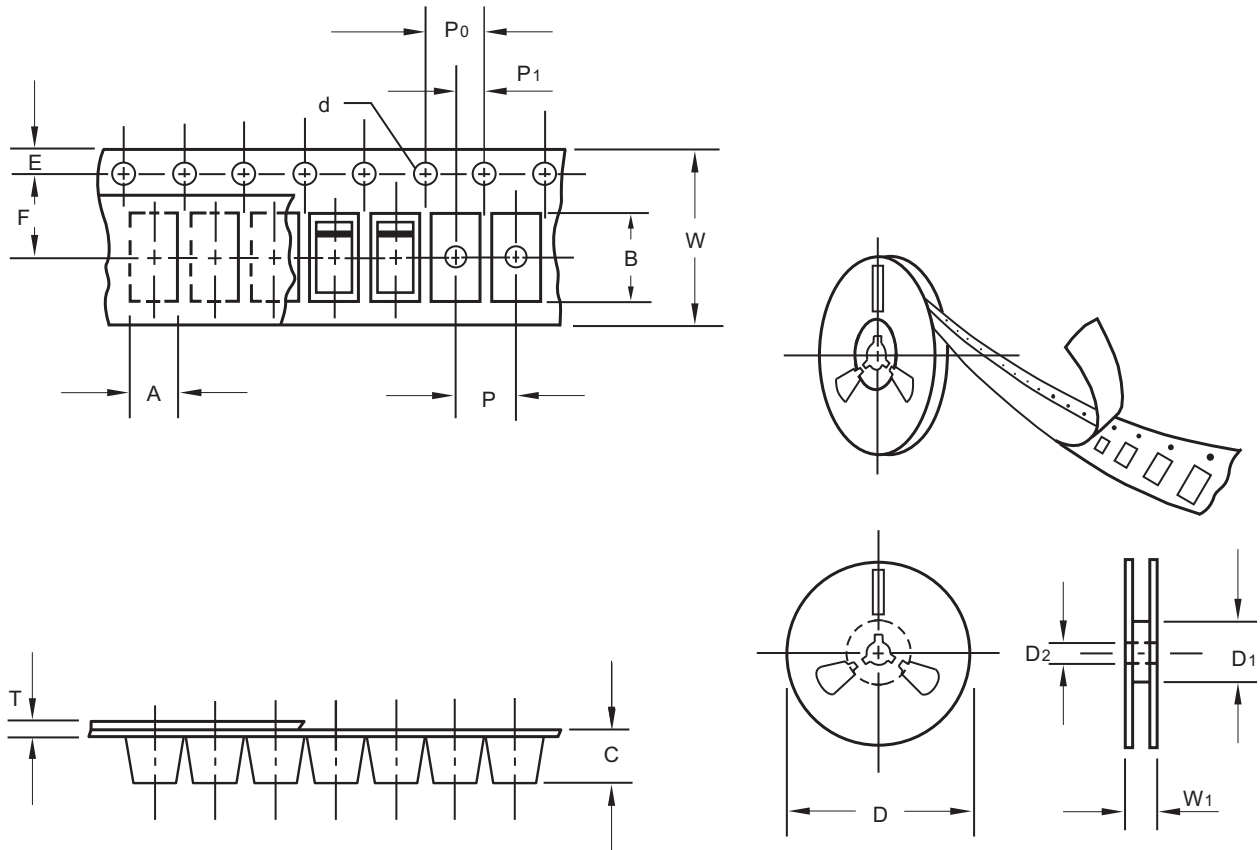
Halogen free product for packing code suffix "H"

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123-L	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)

**Packing information**


unit:mm

Item	Symbol	Tolerance	SOD-123-L
Carrier width	A	0.1	1.90
Carrier length	B	0.1	3.90
Carrier depth	C	0.1	1.68
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.